| L Number | Hits | Search Text | DB | Time stamp |
|-----------|------|---|------------------------|------------------|
| - Manager | 43 | ("6232147" "6455408" "5910644" "6501165" | USPAT; | 2004/04/16 10:28 |
| | | "6620633" "6620731" "5792594" "6218281" | US-PGPUB; | |
| | | "5567981" "6388333" "6064112" "6403457" | EPO; JPO; | |
| | | "6232147" "6335104" "6355104" "6396148" | DERWENT; | |
| | | "6303424" "6372624" "6380555" "6127736" | IBM_TDB | |
| | | "6451624" "6303524").pn. | _ | |
| - | 1362 | (bond or bonding or wirebond or stud near2 | USPAT; | 2004/04/14 15:30 |
| | | bump or solder near2 ball or ball near2 | US-PGPUB; | |
| | | grid) near10 (nickel or vanadium or chromium | EPO; JPO; | |
| | | or copper or ni or v or cr or cu or crcu) | DERWENT; | |
| | | near10 (gold or au or platinum or pt or | IBM_TDB | |
| | | palladium or pd or non-oxidizing or | | |
| | | nonoxidizing) same (redistribution or | | |
| | 205 | redistributing or trace or lead or path) | HODAM | 2004/04/14 16:00 |
| - | 205 | ı ' | USPAT; | 2004/04/14 16:09 |
| - | | bump or solder near2 ball or ball near2 qrid) near8 (nickel or vanadium or chromium | US-PGPUB; EPO; JPO; | |
| | | or copper or ni or v or cr or cu or crcu) | DERWENT; | |
| | | near8 (gold or au or platinum or pt or | IBM TDB | |
| | | palladium or pd or non-oxidizing or | 1511_155 | |
| | | nonoxidizing) same (redistribution or | | |
| | | redistributing or trace) | | |
| - | 22 | ("3761782" "4074342" "4670770" | USPAT | 2004/04/14 15:43 |
| | _ | "4709468" "4829014" "4890157" | | |
| | | "4948754" "5106461" "5137845" | | |
| | | "5198684" "5219117" "5224265" | | |
| | | "5246880" "5327013" "5404265" | | |
| | 1 | "5436411" "5502002" "5505366" | | |
| | | "5604379" "5677576" "5719448" | | |
| | | "5851911").PN. | | |
| - | 228 | (redistribution or redistributing) same | USPAT; | 2004/04/15 16:35 |
| | | (wirebond or wirebonding or wire adj bond or | US-PGPUB; | |
| | | wire adj bonding or solder adj ball or | EPO; JPO; | |
| | | conductive adj ball or ball adj grid or | DERWENT; | |
| | | solder adj bump or conductive adj bump) with | IBM_TDB | |
| _ | _ | (pad or electrode) | IICDATE. | 2004/04/15 15:02 |
| - | 0 | (redistribution or redistributing) near3 (stack or laminate or laminated) same | USPAT; US-PGPUB; | 2004/04/15 15:02 |
| | | (wirebond or wirebonding or wire adj bond or | EPO; JPO; | |
| | | wire adj bonding or solder adj ball or | DERWENT; | |
| | | conductive adj ball or ball adj grid or | IBM TDB | |
| | | solder adj bump or conductive adj bump) with | | |
| | | (pad or electrode) | | |
| - | 14 | (redistribution or redistributing) near3 | USPAT; | 2004/04/15 15:04 |
| | | (stack or laminate or laminated) and | US-PGPUB; | |
| | | (wirebond or wirebonding or wire adj bond or | EPO; JPO; | |
| | | wire adj bonding or solder adj ball or | DERWENT; | |
| | | conductive adj ball or ball adj grid or | IBM_TDB | |
| | | solder adj bump or conductive adj bump) with | | |
| | | (pad or electrode) | | 0004/04/77 77 |
| - | 130 | non-oxidizing near2 (copper or cu) | USPAT; | 2004/04/15 16:33 |
| | 1 | | US-PGPUB; | |
| 1 | | | EPO; JPO; | |
| | | | DERWENT; IBM_TDB | |
| _ | 2 | 6492198.URPN. | USPAT | 2004/04/16 11:03 |
| _ | 0 | (nonoxidizing or non-oxidizing or wettable) | USPAT; | 2004/04/15 16:34 |
| | | near6 (gold or au) near6 electroless\$ and | US-PGPUB; | |
| | | (barrier or ubm) near6 (nickel or ni) near6 | EPO; JPO; | |
| 1 | | electroless\$ | DERWENT; | |
| | | | IBM TDB | |
| - | 34 | (wirebond or wirebonding or wire adj bond or | USPAT; | 2004/04/15 16:39 |
| | | wire adj bonding or solder adj ball or | US-PGPUB; | |
| | | conductive adj ball or ball adj grid or | EPO; JPO; | |
| | | solder adj bump or conductive adj bump) | DERWENT; | |
| | | near6 (pad or electrode) near10 (barrier or | IBM_TDB | |
| | | ubm) and (barrier or ubm or nickel) near6 | | |
| | | (electroless\$ or electro-less\$) | | |

| - | 45 | (wirebond or wirebonding or wire adj bond or | USPAT; | 2004/04/15 16:41 |
|---|----|--|-----------|------------------|
| | | wire adj bonding or solder adj ball or | US-PGPUB; | |
| | | conductive adj ball or ball adj grid or | EPO; JPO; | |
| | | solder adj bump or conductive adj bump) | DERWENT; | |
| | | near6 (pad or electrode) near10 (barrier or | IBM TDB | |
| | | ubm) and (barrier or ubm or nickel or ni or | _ | |
| | | gold or au or wettable or non-oxidizing or | | |
| | | nonoxidizing) near6 (electroless\$ or | | |
| | | electro-less\$) | | |